


- ① Finish: ENIG (Electroless Nickel Immersion Gold), nickel layer $1 \div 4 \mu\text{m}$, gold layer $0.076 \div 0.2 \mu\text{m}$
- ② All gerber files generated as a top view
- ③ Material: Isola IS370 or similar recommended
4. Fabricate according IPC-A-600
5. Non-conductive epoxy ink recommended for silkscreen
6. Silkscreen should not cover any exposed copper, silkscreen gerber data have to be trimmed eventually
7. All holes diameter refer to final diameter after eventual plating

Gerber and drill file extensions table

Gerber files	Description
.GTO	Top side silkscreen
.GTP	Top side solder paste mask
.GTS	Top side solder mask
.GBL	Bottom Layer
.GBS	Bottom side solder mask
.GBP	Bottom side solder paste mask
.GBO	Bottom side silkscreen
.GM1	Board outline
Drill files	
.TXT	Layer pair L1_TOP to L2_BOTTOM Layer

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8 Top copper layer not used (There is no routing). The board is only single sided.

Layer Stack

Material	Layer	Thickness	Dielectric Material	Type	Gerber
	Top Overlay			Legend	GTO
Surface Material	Top Solder	0.0102mm(0.400mil)	Solder Resist	Solder Mask	GTS
Copper	Top Layer	0.0356mm(1.400mil)		Signal	GTL
Core		1.5240mm(60.000mil)	FR-4	Dielectric	
Copper	Bottom Layer	0.0356mm(1.400mil)		Signal	GBL
Surface Material	Bottom Solder	0.0102mm(0.400mil)	Solder Resist	Solder Mask	GBS
	Bottom Overlay			Legend	GBO
Total thickness: 1.6154mm(63.600mil)					

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Layer stack details

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A

A

B

B

C

C

D

D

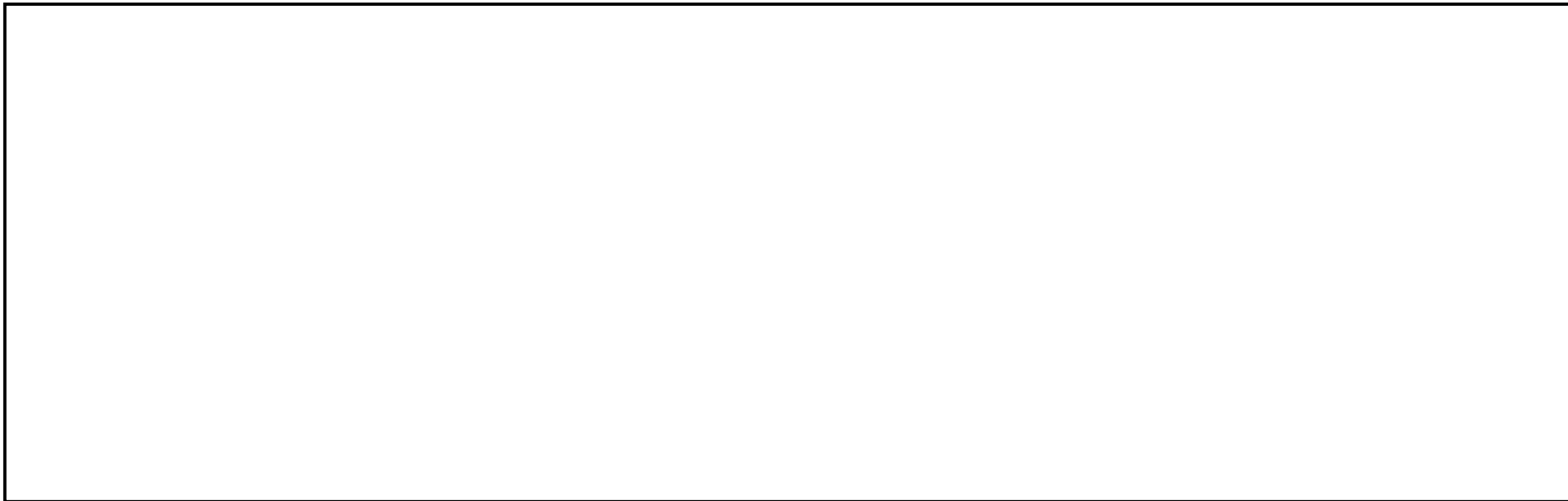
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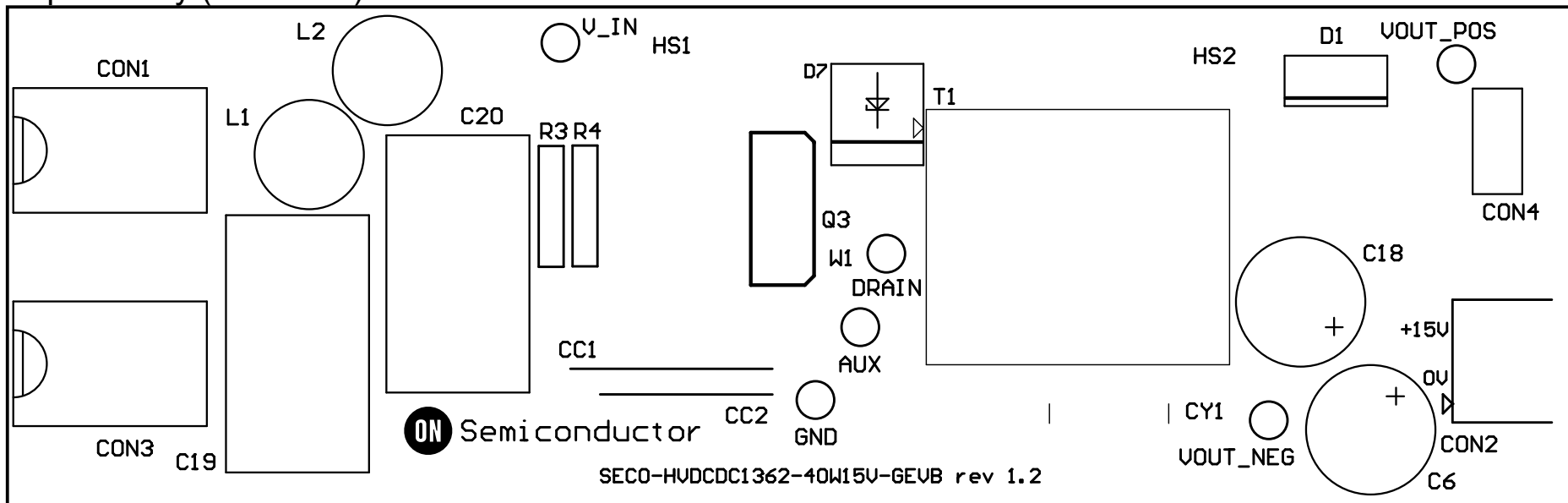
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Top Overlay (Scale 3:2)



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Top side silkscreen - top view

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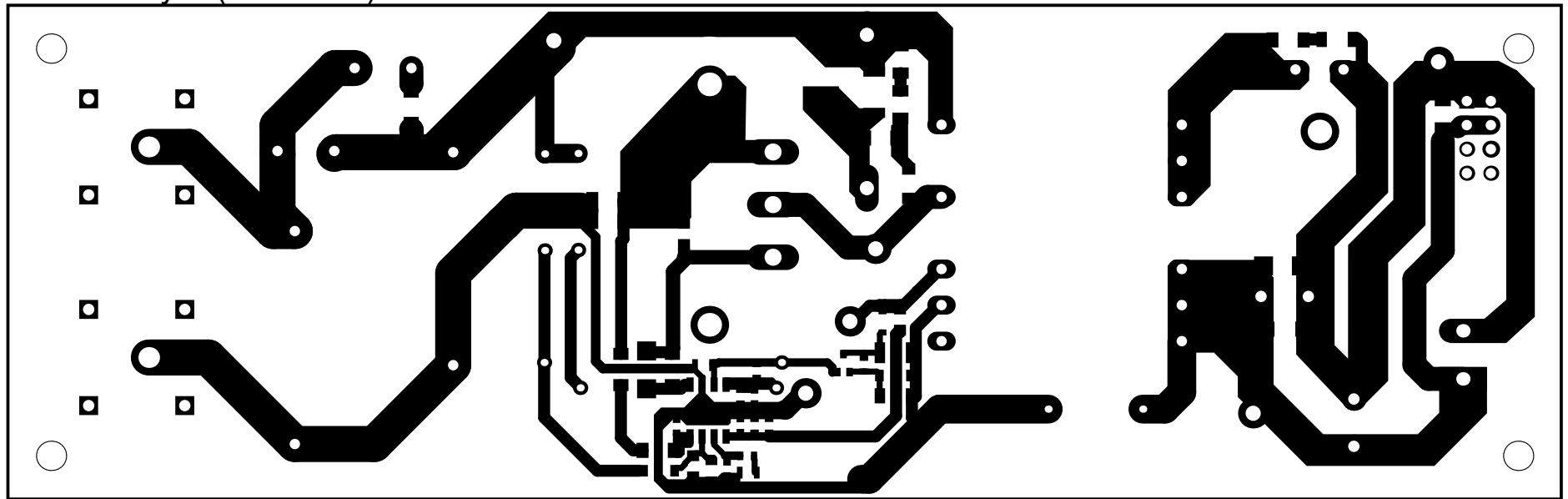
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Bottom Layer (Scale 3:2)



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Bottom Layer - top view

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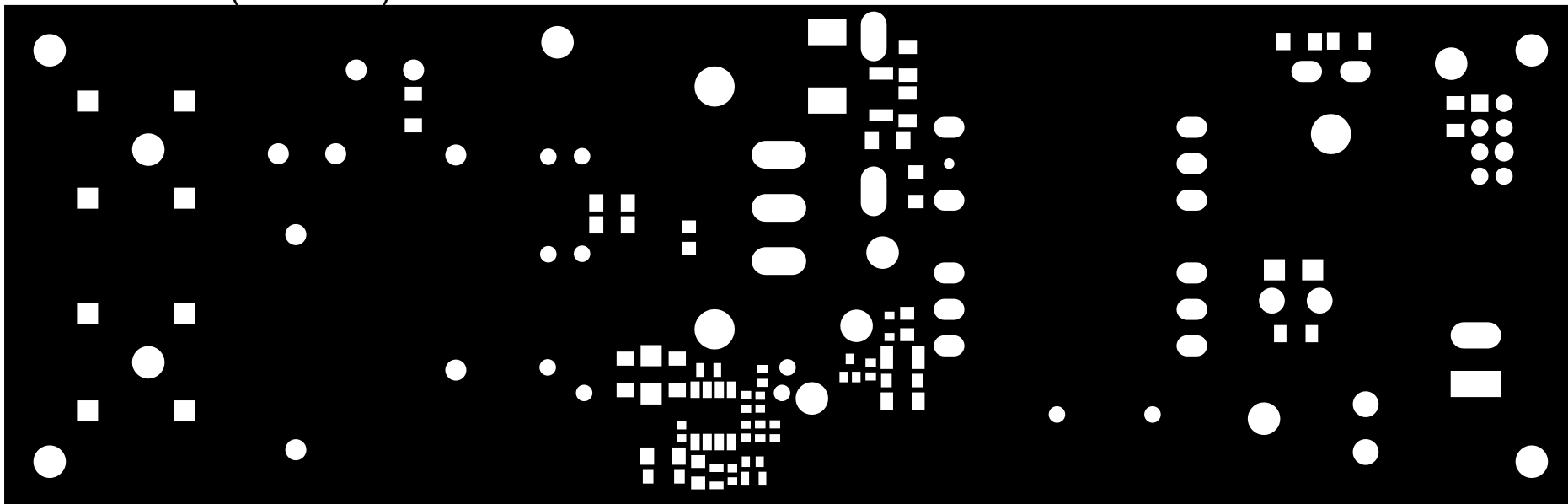
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Bottom Solder (Scale 3:2)



B

B

C

C

D

D

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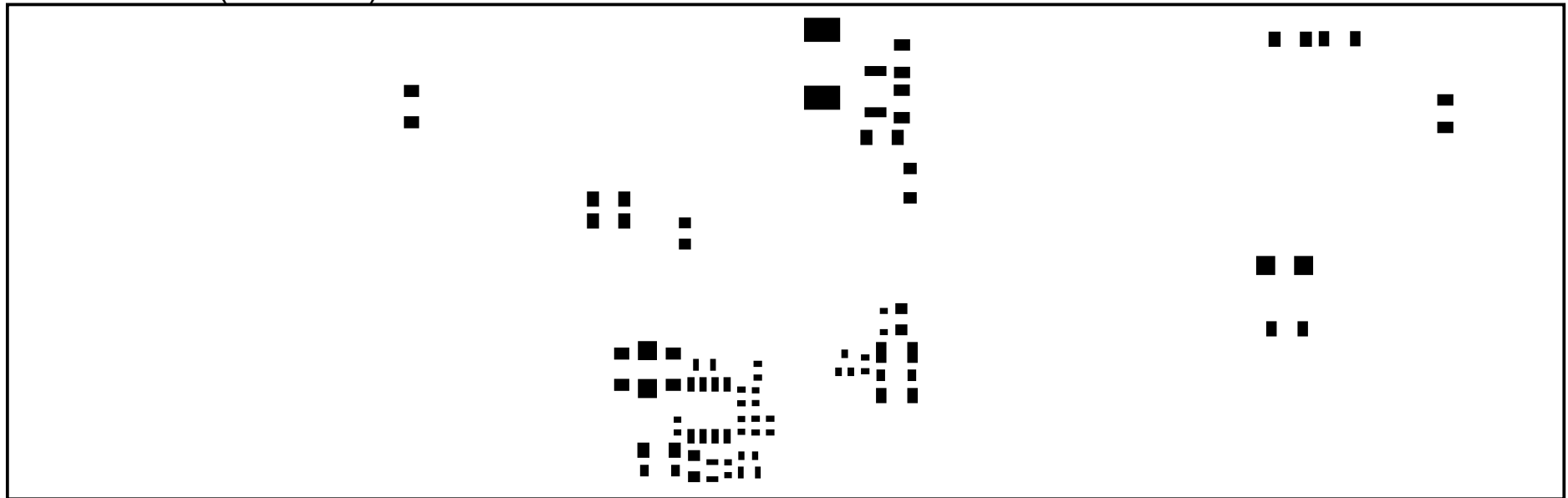
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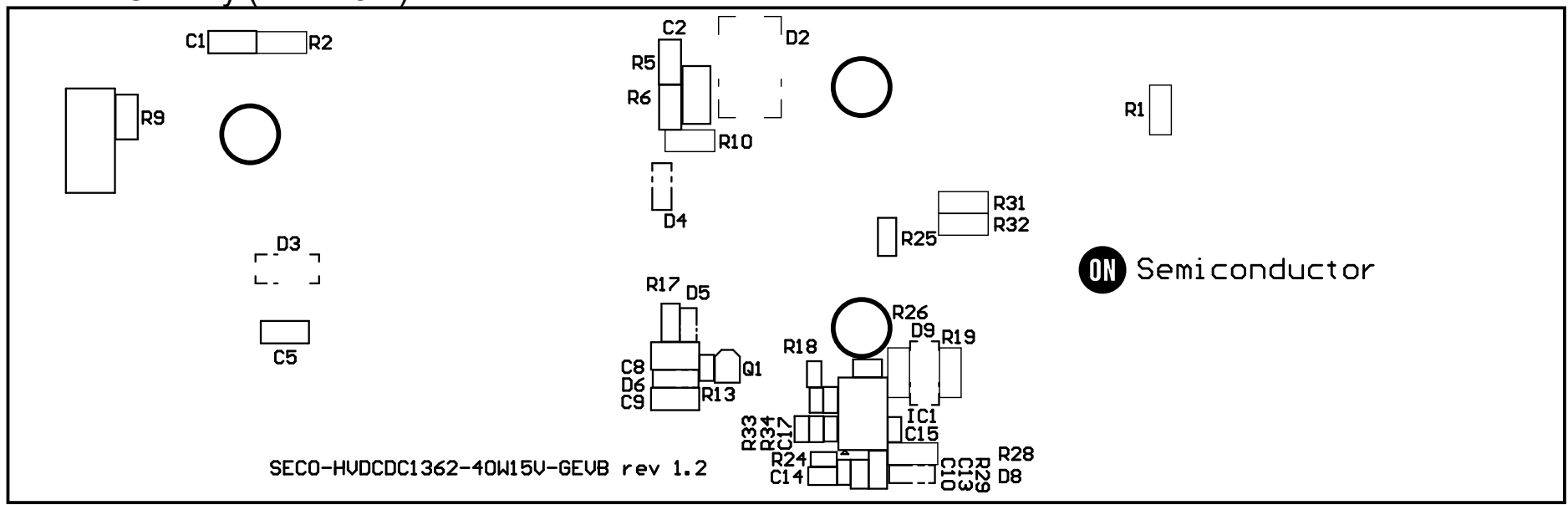
Bottom Paste (Scale 3:2)




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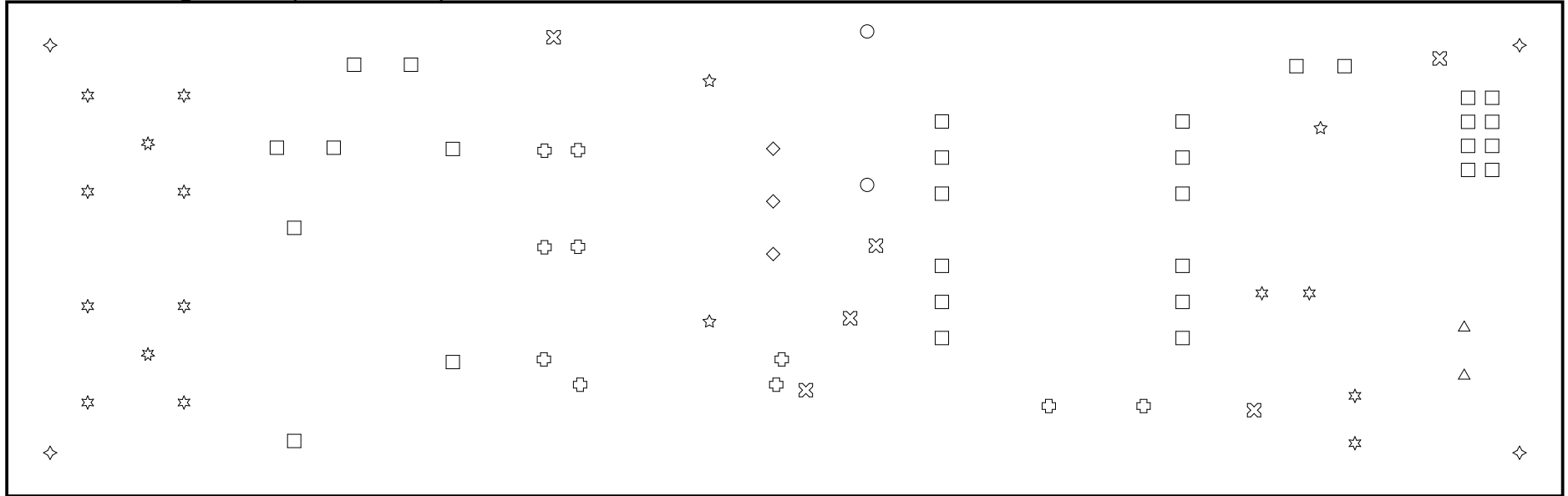


Bottom Overlay (Scale 3:2)



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Drill Drawing View (Scale 3:2)



Drill Table

Symbol	Count	Hole Size	Plated	Drill Layer Pair	Via / Pad	Template
⊕	10	0.762mm(30.0mil)	Plated	Top Layer - Bottom Layer	Pad	c152h76
□	30	1.100mm(43.3mil)	Plated	Top Layer - Bottom Layer	Pad	(Mixed)
☆	12	1.200mm(47.2mil)	Plated	Top Layer - Bottom Layer	Pad	(Mixed)
△	2	1.422mm(56.0mil)	Plated	Top Layer - Bottom Layer	Pad	(Mixed)
○	2	1.500mm(59.1mil)	Plated	Top Layer - Bottom Layer	Pad	r500_250h150r100
⊗	6	1.600mm(63.0mil)	Plated	Top Layer - Bottom Layer	Pad	c320h160
◇	3	1.800mm(70.9mil)	Plated	Top Layer - Bottom Layer	Pad	r270_550h180r100
⊛	2	2.200mm(86.6mil)	Plated	Top Layer - Bottom Layer	Pad	c320h220
☆	3	2.500mm(98.4mil)	Plated	Top Layer - Bottom Layer	Pad	c400h250
◇	4	3.000mm(118.1mil)	Plated	Top Layer - Bottom Layer	Pad	c320h300
	74 Total					

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Drill drawing

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